ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES

IPC-9503

Moisture Sensitivity Classification for Non-IC Components

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A standard developed by IPC

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In May 1995 the IPC's Technical Activities Executive Committee adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:
- Show relationship to DFM & DFE
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:
- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Developed by the Component & Process Compatibility Task Group (5-21c) of the Assembly & Joining Processes Committee (5-20) of IPC

Users of this standard are encouraged to participate in the development of future revisions.

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Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the Component & Process Compatibility Task Group (5-21c) of the Assembly & Joining Processes Committee (5-20) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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